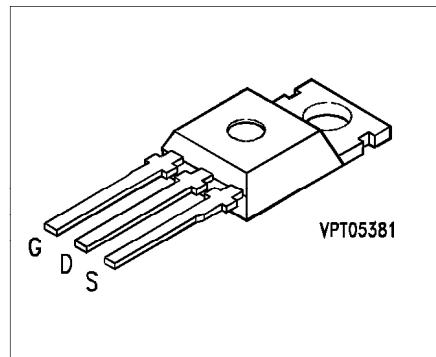


SIPMOS® Power Transistor

BUZ 11 AL

- N channel
- Enhancement mode
- Logic Level
- Avalanche-rated



Type	V_{DS}	I_D	$R_{DS\ (on)}$	Package ¹⁾	Ordering Code
BUZ 11 AL	50 V	26 A	0.055 Ω	TO-220 AB	C67078-S1330-A3

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current, $T_C = 25^\circ\text{C}$	I_D	26	A
Pulsed drain current, $T_C = 25^\circ\text{C}$	$I_{D\ puls}$	104	
Avalanche current, limited by T_j_{max}	I_{AR}	26	
Avalanche energy, periodic limited by $T_j_{(max)}$	E_{AR}	1.9	mJ
Avalanche energy, single pulse $I_D = 26 \text{ A}$, $V_{DD} = 25 \text{ V}$, $R_{GS} = 25 \Omega$ $L = 20.7 \mu\text{H}$, $T_j = 25^\circ\text{C}$	E_{AS}	14	
Gate-source voltage	V_{GS}	± 10	V
Gate-source peak voltage, aperiodic	V_{gs}	± 20	
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	75	W
Operating and storage temperature range	T_j , T_{stg}	- 55 ... + 150	°C

Thermal resistance, chip-case	$R_{th\ JC}$	≤ 1.67	K/W
DIN humidity category, DIN 40 040	-	E	-
IEC climatic category, DIN IEC 68-1	-	55/150/56	

1) See chapter Package Outlines.

Electrical Characteristicsat $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static characteristics

Drain-source breakdown voltage $V_{GS} = 0 \text{ V}, I_D = 0.25 \text{ mA}$	$V_{(\text{BR})\text{DSS}}$	50	—	—	V
Gate threshold voltage $V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	$V_{GS(\text{th})}$	1.5	2.0	2.5	—
Zero gate voltage drain current $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_{DSS}	—	0.1	1.0	μA
—	—	—	10	100	—
Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	—	10	100	nA
Drain-source on-resistance $V_{GS} = 5 \text{ V}, I_D = 13 \text{ A}$	$R_{DS(\text{on})}$	—	0.040	0.055	Ω

Dynamic characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max}}, I_D = 13 \text{ A}$	g_{fs}	10	22	—	S
Input capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	—	1500	2000	pF
Output capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	—	580	840	—
Reverse transfer capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	—	190	300	—
Turn-on time t_{on} , ($t_{\text{on}} = t_{d(\text{on})} + t_r$) $V_{DD} = 30 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 3 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(\text{on})}$	—	25	40	ns
t_r	—	80	120	—	
Turn-off time t_{off} , ($t_{\text{off}} = t_{d(\text{off})} + t_f$) $V_{DD} = 30 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 3 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(\text{off})}$	—	110	160	ns
t_f	—	80	110	—	

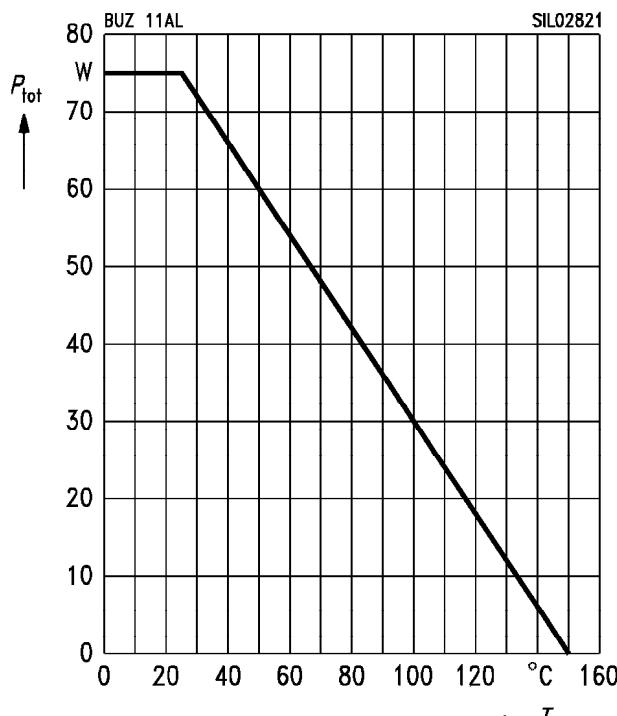
Electrical Characteristics (cont'd)
at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse diode					
Continuous reverse drain current $T_C = 25^\circ\text{C}$	I_S	—	—	26	A
Pulsed reverse drain current $T_C = 25^\circ\text{C}$	I_{SM}	—	—	104	
Diode forward on-voltage $I_S = 52 \text{ A}, V_{GS} = 0 \text{ V}$	V_{SD}	—	1.5	1.8	V
Reverse recovery time $V_R = 30 \text{ V}, I_F = I_S, di_F / dt = 100 \text{ A}/\mu\text{s}$	t_{rr}	—	100	—	ns
Reverse recovery charge $V_R = 30 \text{ V}, I_F = I_S, di_F / dt = 100 \text{ A}/\mu\text{s}$	Q_{rr}	—	0.2	—	μC

Characteristics at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Total power dissipation

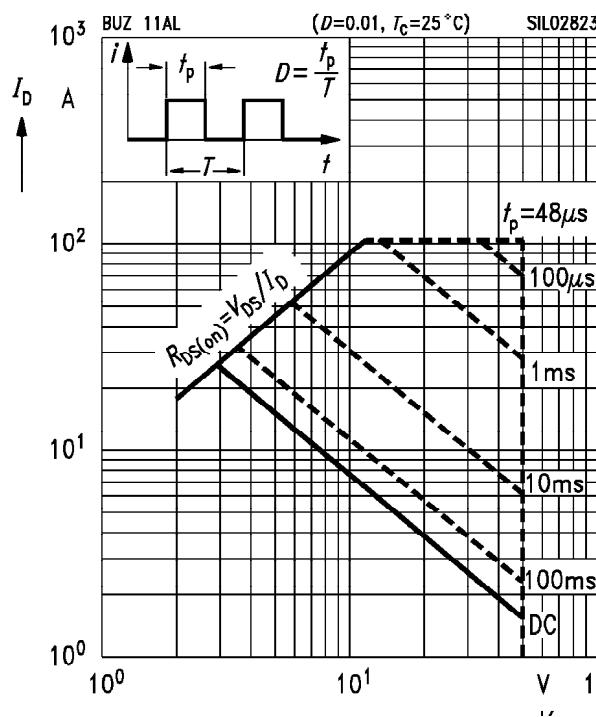
$$P_{\text{tot}} = f(T_C)$$



Safe operating area

$$I_D = f(V_{DS})$$

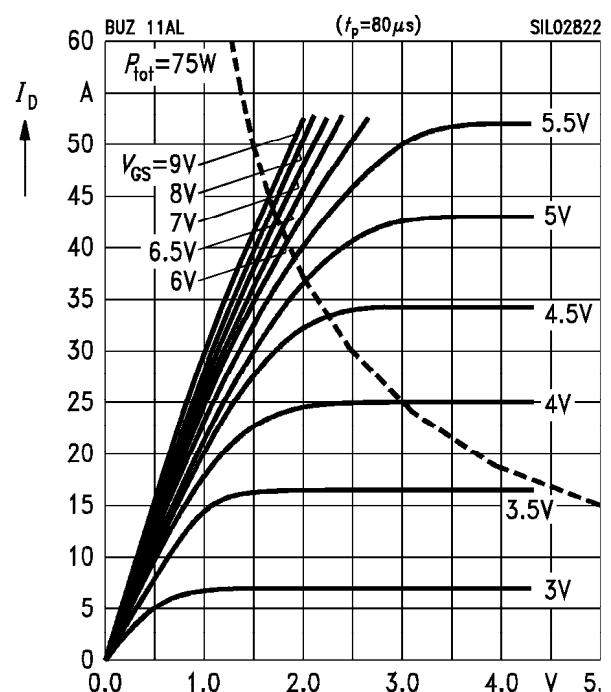
parameter: $D = 0.01, T_C = 25^\circ\text{C}$



Typ. output characteristics

$$I_D = f(V_{DS})$$

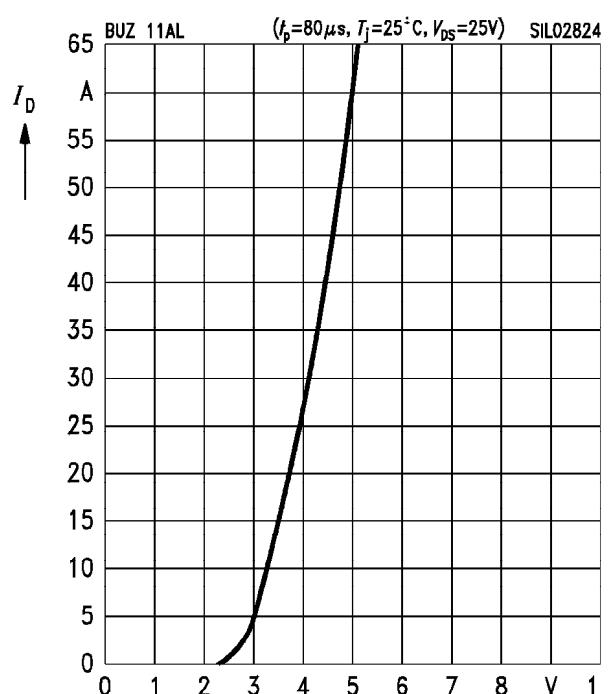
parameter: $t_p = 80\mu\text{s}$



Typ. transfer characteristics

$$I_D = f(V_{GS})$$

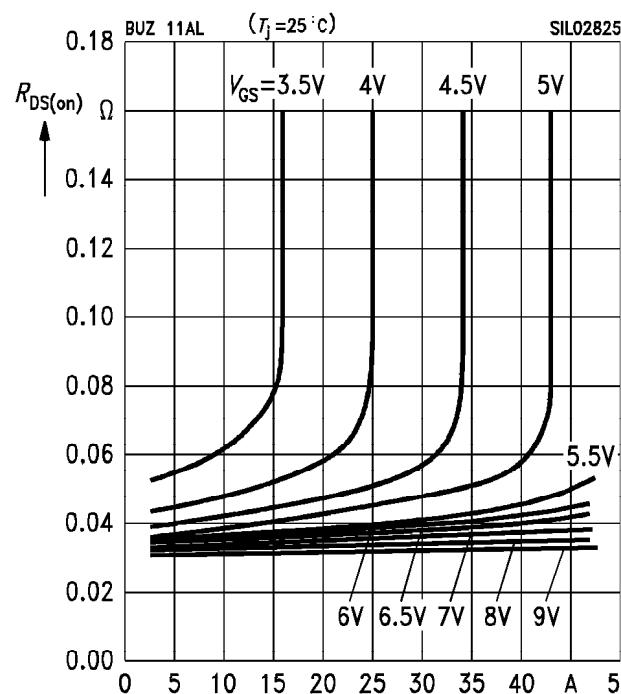
parameter: $t_p = 80\mu\text{s}, V_{DS} = 25\text{V}$



Typ. drain-source on-resistance

$$R_{DS(on)} = f(I_D)$$

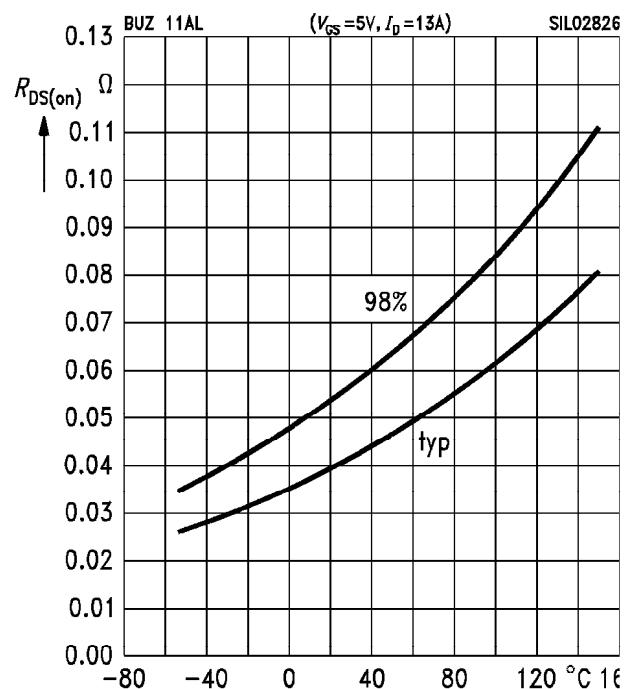
parameter: V_{GS}



Drain-source on-resistance

$$R_{DS(on)} = f(T_j)$$

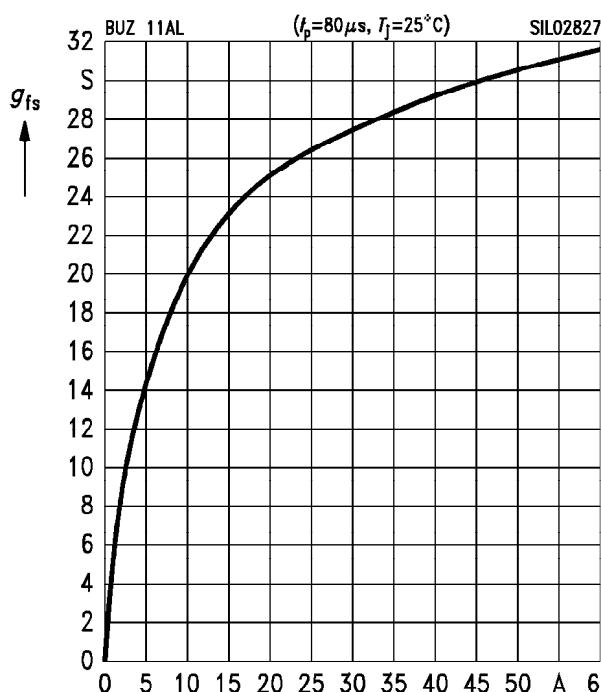
parameter: $I_D = 13 A$, $V_{GS} = 5 V$, (spread)



Typ. forward transconductance

$$g_{fs} = f(I_D)$$

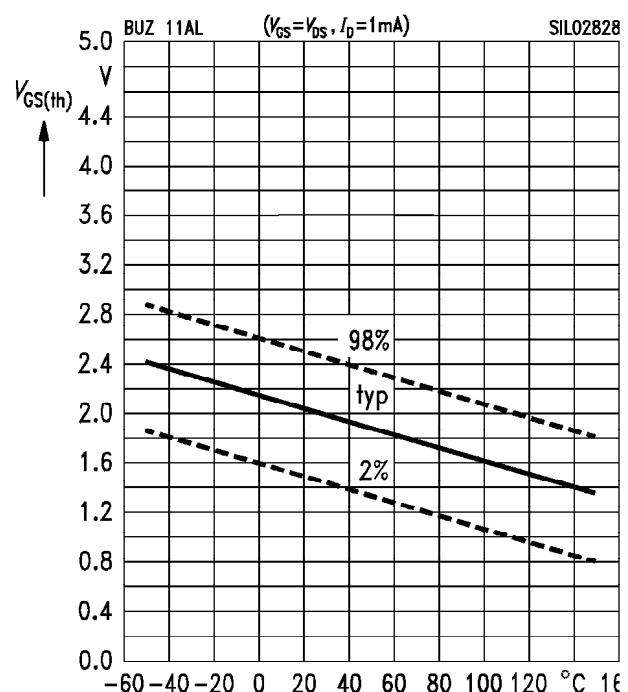
parameter: $t_p = 80 \mu s$



Gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

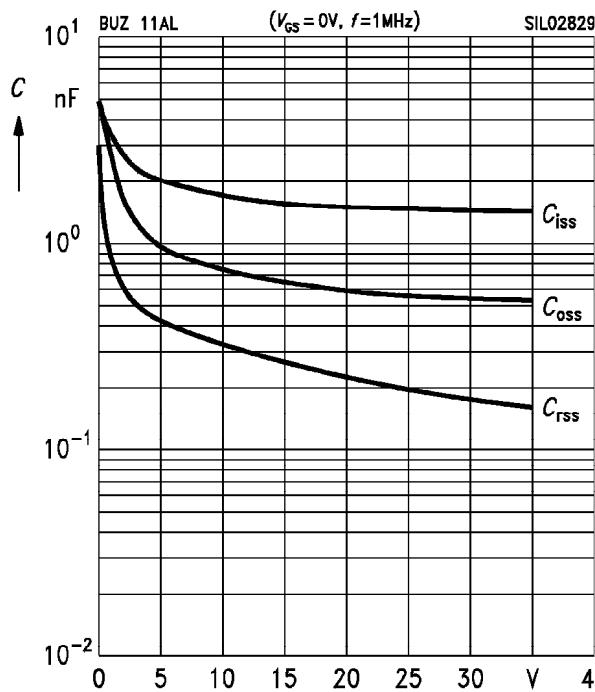
parameter: $V_{GS} = V_{DS}$, $I_D = 1 mA$, (spread)



Typ. capacitances

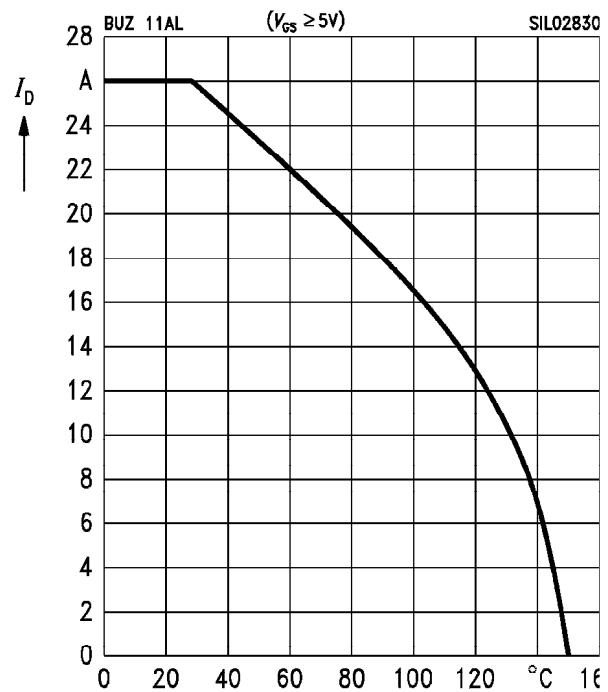
$$C = f(V_{DS})$$

parameter: $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$

**Drain current**

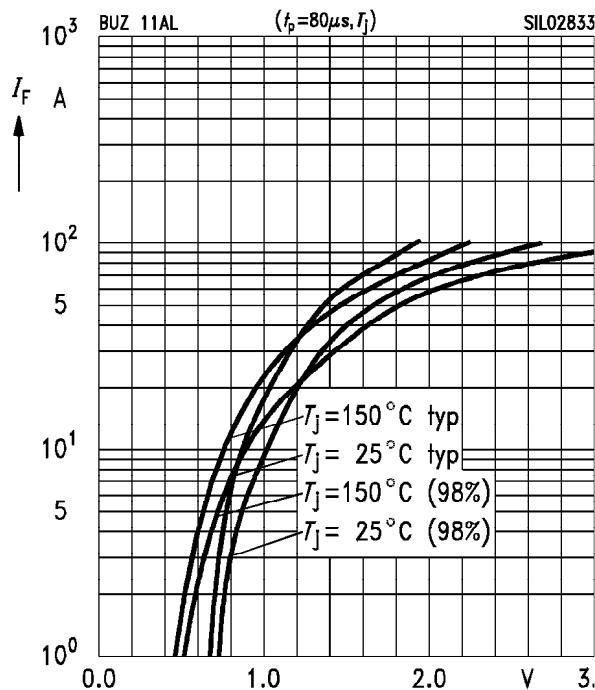
$$I_D = f(T_C)$$

parameter: $V_{GS} \geq 5 \text{ V}$

**Forward characteristics of reverse diode**

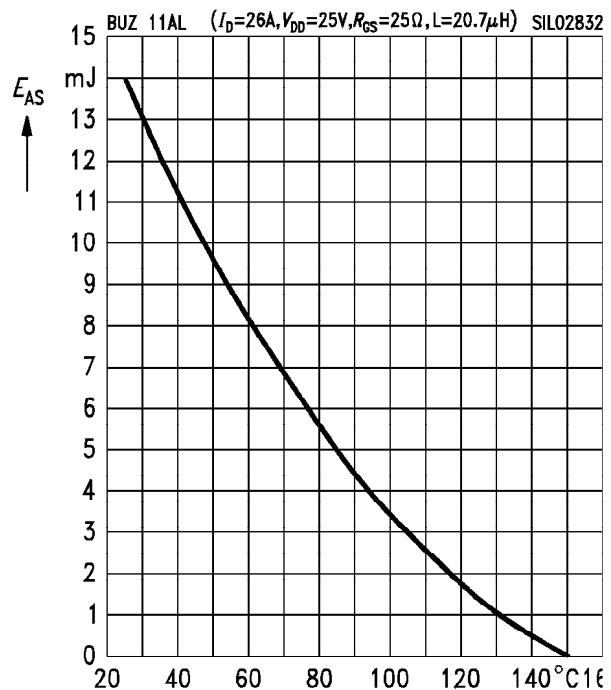
$$I_F = f(V_{SD})$$

parameter: T_j , $t_p = 80 \mu\text{s}$, (spread)

**Avalanche energy $E_{AS} = f(T_j)$**

$$\text{parameter: } I_D = 26 \text{ A}, V_{DD} = 25 \text{ V}$$

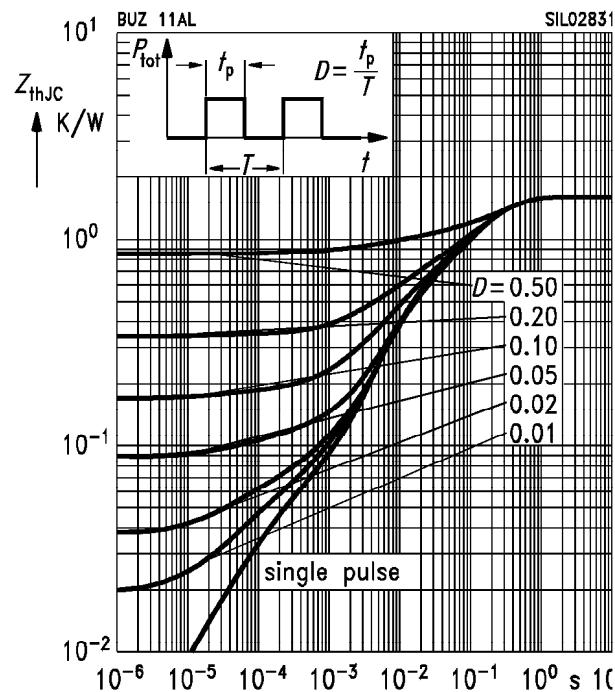
$$R_{GS} = 25 \Omega, L = 20.7 \mu\text{H}$$



Transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

parameter: $D = t_p / T$



Typ. gate charge

$$V_{\text{GS}} = f(Q_{\text{Gate}})$$

parameter: $I_{D \text{ puls}} = 39 \text{ A}$

